

To: Facsimile Number: 703-308-7722

Total Pages Sent 2

From: Texas Instruments Incorporated
Facsimile: 972-917-4418

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Patricia B. Smith, et al. Docket Number: TI-29811

Serial No.: 09/975,639 Art Unit: 2818

Filed: 10/11/01 Examiner: Quoc Dinh Hoang

For: Hydrogen Plasma Photoresist Strip and Polymeric Residue
Cleanup Process for Low Dielectric Constant Materials

FAX RECEIVED

NOV 25 2003

TECHNOLOGY CENTER 2800

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below:

Karen Vertz
Karen Vertz

11-21-03
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET <input type="checkbox"/> NEW APPLICATION <input type="checkbox"/> DECLARATION <input type="checkbox"/> ASSIGNMENT <input type="checkbox"/> FORMAL DRAWINGS <input type="checkbox"/> INFORMAL DRAWINGS <input type="checkbox"/> CONTINUATION APP'N (# Pages) <input type="checkbox"/> DIVISIONAL APP'N	AMENDMENT _____ (# Pages) <input type="checkbox"/> EOT <input type="checkbox"/> NOTICE OF APPEAL <input type="checkbox"/> APPEAL (# Pages) <input type="checkbox"/> ISSUE FEE & PUBLICATION FEE (1 Page) <input type="checkbox"/> REPLY BRIEF (IN TRIPPLICATE) (# Pages) <input type="checkbox"/> ELECTION <input checked="" type="checkbox"/> RCE
NAME OF INVENTOR(S): Patricia B. Smith, et al. TITLE OF INVENTION: Hydrogen Plasma Photoresist Strip and Polymeric Residue Cleanup Process for Low Dielectric Constant Materials	
RECEIPT DATE & SERIAL NO.: Serial No.: 09/975,639 Filing Date: 10/11/01	
TI FILE NO.: TI-29811 DEPOSIT ACCT. NO.: 20-0668 FAXED: 11-21-03 DUE: 11-25-03 ATTY/SECY: RAK/kjv	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265-5474